measurement, the on-axis alignment device described with reference to Figures 1 and 3 may be used, with which the position of a mask mark with respect to substrate holder mark is then determined. Not only the double alignment-measuring device of Fig. 3, but also a single alignment-measuring device as described in US Patent 4,251,160 may be used.

IN THE CLAIMS

Please amend the claims as follows:

A2

3. A method as claimed in claim 1, characterized in that use is made of gratings for the substrate alignment mark, the additional alignment mark and the reference alignment mark.

4. A method as claimed in claim 1, characterized in that the additional alignment mark is a latent mark.

A3

6. A method as claimed in claim 1, characterized in that it is based on the on-axis alignment principle.

#4

8. A method as claimed in claim 1, characterized in that it is based on the off-axis alignment principle.

9. A method of manufacturing devices in at least one layer of a substrate, which method comprises at least one set of the following successive steps:

- aligning a mask provided with a mask pattern comprising pattern features corresponding to a device feature to be configured in said layer;
- imaging, by means of projection radiation, the mask pattern in a radiation-sensitive layer on the substrate, and